

Sound Processor with Built-in 3-band Equalizer BD37533FV

General Description

BD37533FV is a sound processor with built-in 3-band equalizer for car audio. A stereo input selector is available that functions to switch single end input and ground isolation input, input-gain control, main volume, loudness, 5ch fader volume, LPF for subwoofer and mixing input. Moreover, "Advanced switch circuit", which is an original ROHM technology, can reduce various switching noise (ex. No-signal, low frequency like 20Hz & large signal inputs). Also, "Advanced switch" makes microcomputer control easier, and constructs a high quality car audio system.

Features

- Reduced switching noise of input gain control, mute, main volume, fader volume, bass, middle, treble, loudness by using advanced switch circuit
- Built-in differential input selector that can make various combination of single-ended / differential input.
- Built-in ground isolation amplifier inputs, which is ideal for external stereo input.
- Built-in input gain controller reduces volume switching noise of a portable audio input.
- Decreased number of external components due to built-in 3-band equalizer filter, LPF for subwoofer and loudness filter. It is possible to freely control the Q, Gv, fo of the 3-band equalizer, fc of the LPFand Gv of loudness by I²C BUS control.
- A gain adjustment quantity of ±20dB with a 1 dB step gain adjustment is possible for the bass, middle and treble.
- Equipped with terminals for the subwoofer outputs. Also, the audio signal outputs of the front, rear and subwoofer can be chosen using the I²C BUS control
- Built-in mixing input, mixing attenuator.
- Energy-saving design resulting in low current consumption is achieved utilizing the BiCMOS process. It has the advantage in quality over scaling down the power heat control of the internal regulators
- Input pins and output pins are organized and separately laid out to keep the signal flow in one direction which consequently, simplify pattern layout of the set board and decrease the board dimensions
- It is possible to control I²C BUS with 3.3V / 5V

Applications

It is optimal for car audio systems. It can also be used for audio equipment of mini Compo, micro Compo, TV etc

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Key Specifications	
Power Supply Voltage Range:	7.0V to 9.5V
Circuit Current (No Signal):	38mA (Typ)
Total Harmonic Distortion 1:	
(FRONT,REAR)	0.001% (Typ)
Total Harmonic Distortion 2:	
(SUBWOOFER)	0.002% (Typ)
Maximum Input Voltage:	2.3Vrms (Typ)
Cross-talk Between Selectors:	-100dB (Typ)
Volume Control Range:	+15dB to -79dB
Output Noise Voltage 1:	
(FRONT,REAR)	3.8µVrms (Typ)
 Output Noise Voltage 2: 	
(SUBWOOFER)	4.8µVrms (Typ)
Residual Output Noise Voltage:	1.8uVrms (Tvp)

- Operating Temperature Range: -40°C to +85°C

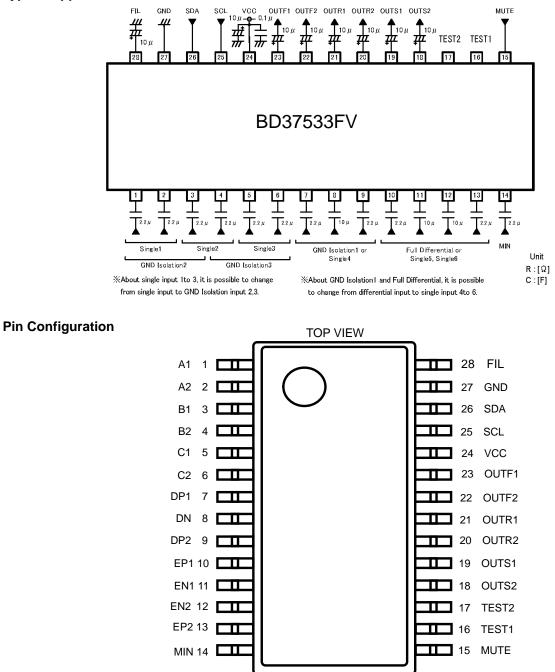
Package

W(Typ) x D(Typ) x H(Max)



OProduct structure : Silicon monolithic integrated circuit OThis product has no designed protection against radioactive rays

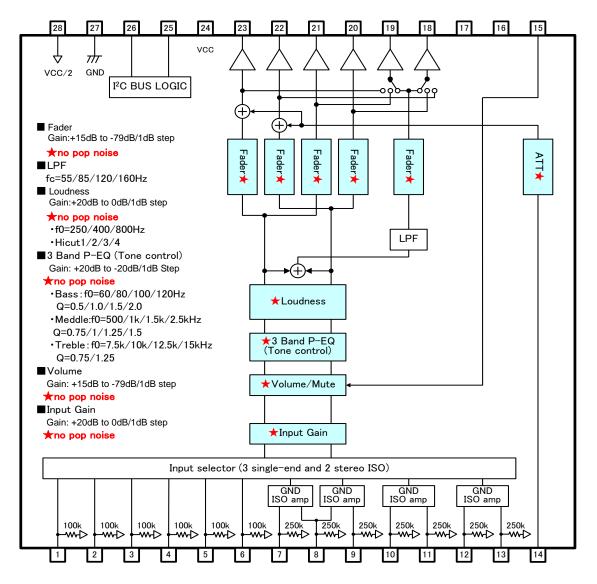
Typical Application Circuit



Pin Descriptions

Pin No.	Pin Name	Description	Pin No.	Pin Name	Description
1	A1	A input terminal of 1ch	15	MUTE	External compulsory mute terminal
2	A2	A input terminal of 2ch	16	TEST1	Test Pin
3	B1	B input terminal of 1ch	17	TEST2	Test Pin
4	B2	B input terminal of 2ch	18	OUTS2	Subwoofer output terminal of 2ch
5	C1	C input terminal of 1ch	19	OUTS1	Subwoofer output terminal of 1ch
6	C2	C input terminal of 2ch	20	OUTR2	Rear output terminal of 2ch
7	DP1	D positive input terminal of 1ch	21	OUTR1	Rear output terminal of 1ch
8	DN	D negative input terminal	22	OUTF2	Front output terminal of 2ch
9	DP2	D positive input terminal of 2ch	23	OUTF1	Front output terminal of 1ch
10	EP1	E positive input terminal of 1ch	24	VCC	Power supply terminal
11	EN1	E negative input terminal of 1ch	25	SCL	I ² C Communication clock terminal
12	EN2	E negative input terminal of 2ch	26	SDA	I ² C Communication data terminal
13	EP2	E positive input terminal of 2ch	27	GND	GND terminal
14	MIN	Mixing input terminal	28	FIL	VCC/2 terminal

Block Diagram



Absolute Maximum Ratings (Ta=25°C)

Parameter	Parameter Symbol Rating		Unit
Power supply Voltage	Vcc	10.0	V
Input voltage	V _{IN}	V _{cc} +0.3 to GND-0.3	V
Power Dissipation	Pd	1.06 ^(Note 1)	W
Storage Temperature	Tstg	-55 to +150	°C

(Note 1) When mounted on the standar board (70 x 70 x 1.6(mm³), derate by 8.5mW/°C for Ta above 25°C.

Thermal resistance θja = 117.6(°C/W)

Material : A FR4 grass epoxy board (3% or less of copper foil area)

Caution: Operating the IC over the absolute maximum ratings may damage the IC. The damage can either be a short circuit between pins or an open circuit between pins and the internal circuitry. Therefore, it is important to consider circuit protection measures, such as adding a fuse, in case the IC is operated over the absolute maximum ratings.

Recommended Operating Conditions

Parameter	Parameter Symbol Limit		Unit
Power Supply Voltage	Vcc	7.0 to 9.5	V
Temperature	Topr	-40 to +85	°C

Electrical Characteristics

(Unless otherwise noted, Ta=25°C, V_{CC}=8.5V, f=1kHz, V_{IN}=1Vrms, Rg=600Ω, R_L=10kΩ, A1 input, Input gain 0dB, Mute OFF, Volume 0dB, Tone control 0dB, Loudness 0dB, LPF OFF, Mixing OFF, Fader 0dB)

			,	Limit	y = ,		
BLOCK	Parameter	Symbol	Min	Тур	Max	Unit	Conditions
	Circuit Current	lq	-	38	48	mA	No signal
	Voltage Gain	Gv	-1.5	0	+1.5	dB	Gv=20log(Vout/VIN)
	Channel Balance	CB	-1.5	0	+1.5	dB	$CB = G_{V1} - G_{V2}$
	Total Harmonic Distortion 1 (FRONT,REAR)	THD+N1	-	0.001	0.05	%	V _{OUT} =1Vrms BW=400Hz-30KHz
	Total Harmonic Distortion 2 (SUBWOOFER)	THD+N2	-	0.002	0.05	%	V _{OUT} =1Vrms BW=400Hz-30KHz
SAL	Output Noise Voltage 1 (FRONT,REAR) *	V _{NO1}	-	3.8	15	µVrms	Rg = 0Ω BW = IHF-A
GENERAL	Output Noise Voltage 2 (SUBWOOFER) *	V _{NO2}	-	4.8	15	µVrms	Rg = 0Ω BW = IHF-A
Ū	Residual Output Noise Voltage *	V _{NOR}	-	1.8	10	μVrms	Fader = -∞dB Rg = 0Ω BW = IHF-A
	Cross-talk Between Channels *	СТС	-	-100	-90	dB	Rg = 0Ω CTC=20log(V _{OUT} /V _{IN}) BW = IHF-A
	Ripple Rejection	RR	-	-70	-40	dB	f=1kHz V _{RR} =100mVrms RR=20log(V _{CC} IN/V _{OUT})
	Input Impedance(A, B, C)	RIN_S	70	100	130	kΩ	
	Input Impedance (D, E)	R _{IN_D}	175	250	325	kΩ	
TOR	Maximum Input Voltage	VIM	2.1	2.3	-	Vrms	V _{IM} at THD+N(V _{OUT})=1% BW=400Hz-30KHz
- SELECTOR	Cross-talk Between Selectors *	CTS	-	-100	-90	dB	$Rg = 0\Omega$ CTS=20log(V _{OUT} /V _{IN}) BW = IHF-A
INPUT	Common Mode Rejection Ratio * (D, E)	CMRR	50	65	-	dB	XP1 and XN input XP2 and XN input CMRR=20log(V_{IN}/V_{OUT}) BW = IHF-A,[*X···D,E]

Electrical Characteristics – continued

X				Limit			
BLOCK	Parameter	Symbol	Min	Тур	Max	Unit	Conditions
GAIN	Minimum Input Gain	Gin_min	-2	0	+2	dB	Input gain 0dB V _{IN} =100mVrms G _{IN} =20log(V _{OUT} /V _{IN})
INPUT GAIN	Maximum Input Gain	Gin_max	+18	+20	+22	dB	Input gain +20dB V _{IN} =100mVrms G _{IN} =20log(V _{OUT} /V _{IN})
	Gain Set Error	GIN_ERR	-2	0	+2	dB	GAIN=+20dB to +1dB
MUTE	Mute Attenuation *	GMUTE	-	-105	-85	dB	Mute ON G _{MUTE} =20log(V _{OUT} /V _{IN}) BW = IHF-A
	Maximum Gain	Gv_max	13	15	17	dB	Volume = 15dB V _{IN} =100mVrms Gv=20log(V _{OUT} /V _{IN})
VOLUME	Maximum Attenuation *	G_{V_MIN}	-	-100	-85	dB	Volume = $-\infty dB$ $G_V=20log(V_{OUT}/V_{IN})$ BW = IHF-A
ž	Attenuation Set Error 1	Gv_err1	-2	0	+2	dB	GAIN & ATT=+15dB to -15dB
	Attenuation Set Error 2	Gv_err2	-3	0	+3	dB	ATT=-16dB to -47dB
	Attenuation Set Error 3	Gv_err3	-4	0	+4	dB	ATT=-48dB to -79dB
	Maximum Boost Gain	G _{B_BST}	18	20	22	dB	Gain=+20dB f=100Hz V _{IN} =100mVrms GB=20log (V _{OUT} /V _{IN})
BASS	Maximum Cut Gain	G в_сит	-22	-20	-18	dB	Gain=-20dB f=100Hz V _{IN} =2Vrms GB=20log (V _{OUT} /V _{IN})
	Gain Set Error	G_{B_ERR}	-2	0	+2	dB	Gain=+20dB to -20dB f=100Hz
ш	Maximum Boost Gain	G _{M_BST}	18	20	22	dB	Gain=+20dB f=1kHz V _{IN} =100mVrms GM=20log (V _{OUT} /V _{IN})
MIDDLE	Maximum Cut Gain	G м_сит	-22	-20	-18	dB	Gain=-20dB f=1kHz V _{IN} =2Vrms GM=20log (V _{OUT} /V _{IN})
	Gain Set Error	Gm_err	-2	0	+2	dB	Gain=+20dB to -20dB f=1kHz
щ	Maximum Boost Gain	GT_BST	18	20	22	dB	Gain=+20dB f=10kHz V _{IN} =100mVrms GT=20log (V _{OUT} /V _{IN})
TREBL	Maximum Cut Gain	GT_CUT	-22	-20	-18	dB	Gain=-20dB f=10kHz V _{IN} =2Vrms GT=20log (V _{OUT} /V _{IN})
	Gain Set Error	Gt_err	-2	0	+2	dB	Gain=+20dB to -20dB f=10kHz
	Input Impedance	RIN_M	19	27	35	kΩ	
<u>0</u>	Maximum Input Voltage	Vім_м	2.0	2.2	-	Vrms	V _{IM} at THD+N(V _{OUT})=1% BW=400Hz-30KHz
MIXING	Maximum Attenuation *	Gmx_min	-	-100	-85	dB	MIX=OFF G _{MX} =20log(V _{OUT} /V _{IN}) BW=INF-A
	Maximum Gain	G _{MX_MAX}	5	7	9	dB	ATT=+7dB G _{MX} =20log(V _{OUT} /V _{IN})

Electrical Characteristics - continued

OCK				Limit			
BLO(Parameter	Symbol	Min	Тур	Max	Unit	Conditions
ER	Maximum Boost Gain	G _{F_BST}	13	15	17	dB	Fader=15dB V _{IN} =100mVrms G _F =20log(V _{OUT} /V _{IN})
SUBWOOFE	Maximum Attenuation *	Gf_min	-	-100	-90	dB	fader = -∞dB G _F =20log(V _{OUT} /V _{IN}) BW = IHF-A
I IS	Gain Set Error	G_{F_ERR}	-2	0	+2	dB	Gain=+15dB to +1dB
<u> </u>	Attenuation Set Error 1	GF_ERR1	-2	0	+2	dB	ATT=-1dB to -15dB
ШК	Attenuation Set Error 2	GF_ERR2	-3	0	+3	dB	ATT=-16dB to -47dB
FADI	Attenuation Set Error 3	G _{F_ERR3}	-4	0	+4	dB	ATT=-48dB to -79dB
μ	Output Impedance	Rout	-	-	50	Ω	V _{IN} =100mVrms
	Maximum Output Voltage	Vом	2	2.2	-	Vrms	THD+N=1% BW=400Hz-30KHz
SS	Maximum Gain	Gl_max	17	20	23	dB	Gain 20dB V _{IN} =100mVrms G _L =20log(V _{OUT} /V _{IN})
LOUDNE	Gain Set Error	Gl_err	-2	0	+2	dB	Gain=+20dB to +1dB

VP-9690A (Average value detection, effective value display) filter by Matsushita Communication is used for * measurement. Phase between input / output is same.

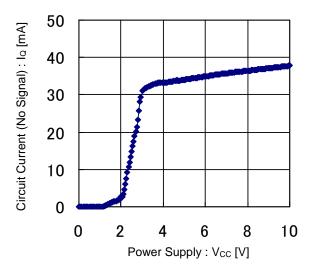
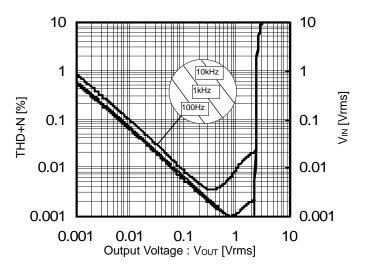
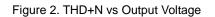


Figure 1. Circuit Current (No Signal) vs Power Supply Voltage





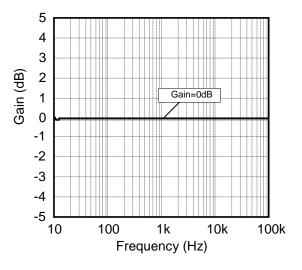


Figure 3. Gain vs Frequency

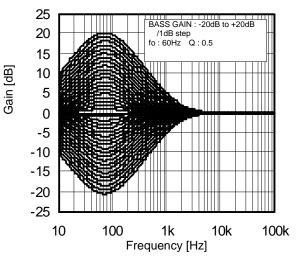
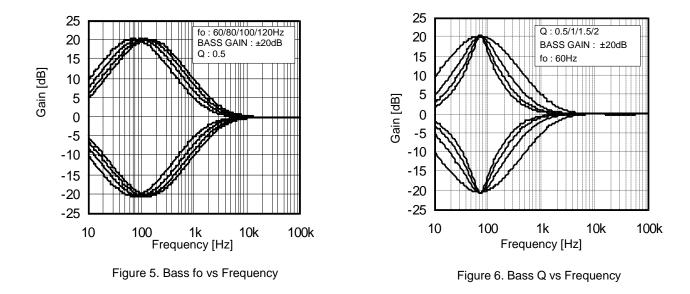
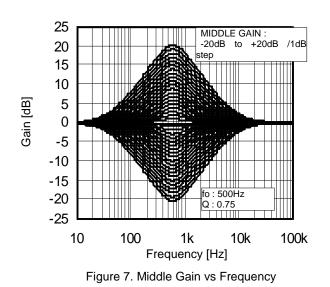


Figure 4. Bass Gain vs Frequency





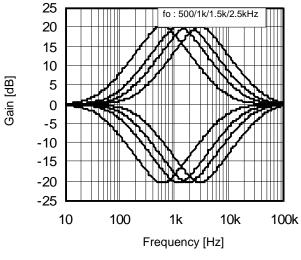
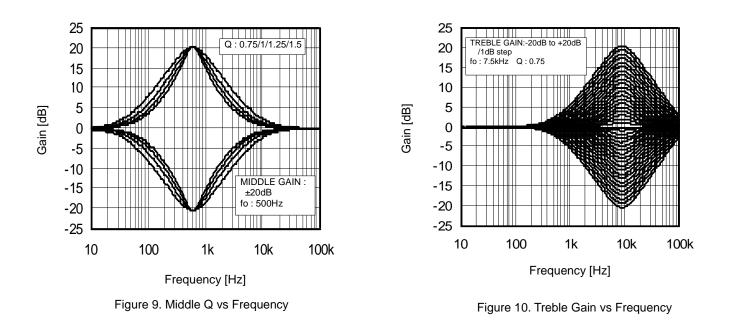


Figure 8. Middle fo vs Frequency



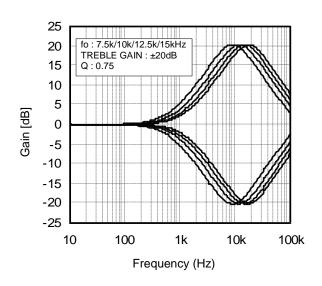


Figure 11. Treble fo vs Frequency

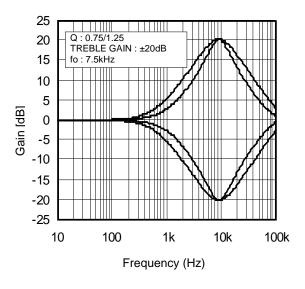


Figure 12. Treble Q vs Frequency

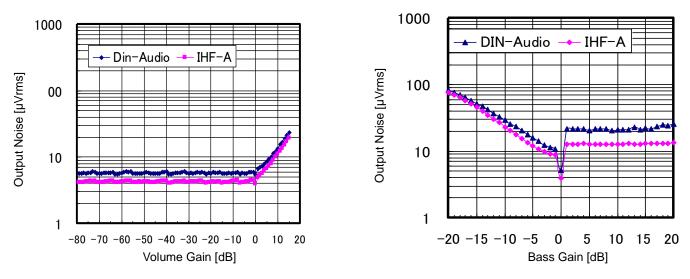
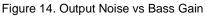


Figure 13. Output Noise vs Volume Gain



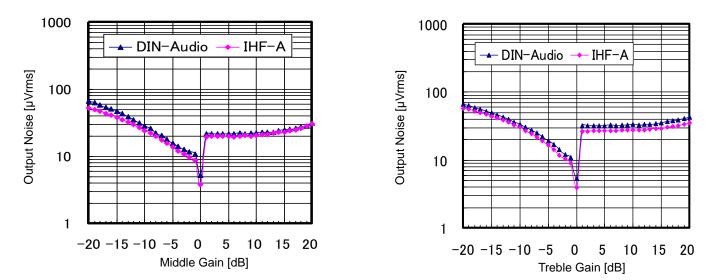


Figure 15. Output Noise vs Middle Gain

Figure 16. Output Noise vs Treble Gain

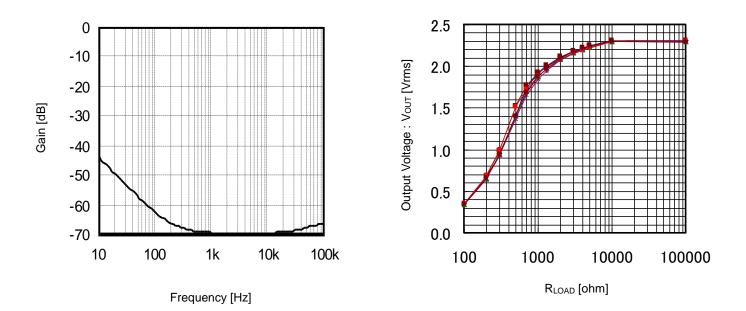


Figure 17. CMRR vs Frequency

Figure 18. Output Voltage vs R_{LOAD}

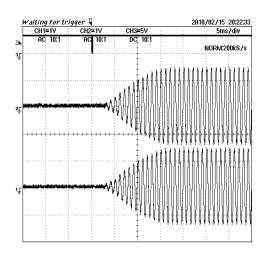


Figure 19. Advanced Switch 1

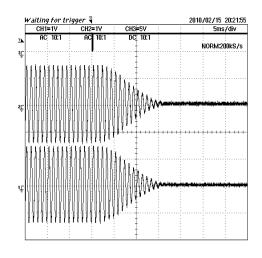


Figure 20. Advanced Switch 2

Timing Chart

CONTROL SIGNAL SPECIFICATION

(1) Electrical Specifications and Timing for Bus Lines and I/O Stages

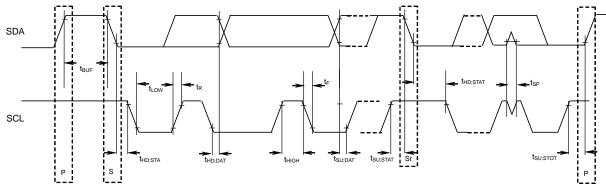


Figure 21. Definition of Timing on the I²C-bus

Table 1 Characteristics of the SDA and SCL bus lines for I²C-bus devices (Unless specified particularly, Ta=25°C, Vcc=8.5V)

	Parameter	Symbol	Fast-mode	Unit	
	Faldineter	Symbol	Min	Max	Onit
1	SCL clock frequency	fscl	0	400	kHz
2	Bus free time between a S TO P and START condition	t BUF	1.3	-	μS
3	Hold time (repeated) START condition. After this period, the first clock	tur	0.6		μS
3	pulse is generated	t hd;sta	0.6	-	μο
4	LOW period of the SCL clock	t _{LOW}	1.3	-	μS
5	HIGH period of the SCL clock	tнigн	0.6	-	μS
6	Set-up time for a repeated START condition	tsu;sta	0.6	-	μS
7	Data hold time:	t _{HD;DAT}	0.06 (Note)	-	μS
8	Data set-up time	tsu;dat	120	-	ns
9	Set-up time for STOP condition	tsu;sто	0.6	-	μS

All values referred to VIH Min and VIL Max Levels (see Table 2).

(Note) The device must internally provide a hold time of at least 300 ns for the SDA signal (referred to the VIH Min of the SCL signal) in order to bridge the undefined region of the falling edge of SCL. About 7(t_{HD;DAT}), 8(t_{SU;DAT}), make the setup in which the margin is fully in .

Table 2 Characteristics of the SDA and SCL I/O stages for I²C-bus devices

	Parameter	Symbol	Fast-mod	Unit	
	Parameter	Symbol	Min	Max	Unit
10	LOW level input voltage:	VIL	-0.3	+1	V
11	HIGH level input voltage:	VIH	2.3	5	V
12	Pulse width of spikes which must be suppressed by the input filter.	tsp	0	50	ns
13	LOW level output voltage: at 3mA sink current	V _{OL1}	0	0.4	V
14	Input current each I/O pin with an input voltage between 0.4V and 4.5V.	lı	-10	+10	μA

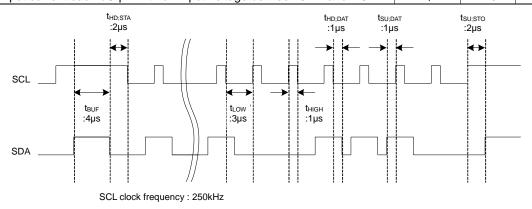


Figure 22. A Command Timing Example in the I²C Data Transmission

(2) <u>I²C BUS FORMAT</u>

	MSB LSE	5	MSB	LSB	MSB	LSB			
S	Slave Address	Α	Select Addres	s A	Data	1	А	Р	
1bit	8bit	1bit	8bit	1bit	8bi	t	1bit	1bit	
	S = Start conditions (Recognition of start bit)								
	Slave Address = Recognition of slave address. 7 bits in upper order are voluntary.								
		Th	The least significant bit is "L" due to writing.						
	А	= AC	KNOWLEDGE bit	(Recognit	ion of acknowl	edgement)			
	Select Address	s = Se	elect every of volur	ne, bass a	nd treble.				
	Data = Data on every volume and tone.								
	Р	= St	op condition (Reco	gnition of	stop bit)				

(3) <u>I²C BUS Interface Protocol</u>

(a) Basic form

(4)	ay Basis Ionn										
S	Slave Addres	s A	Se	ect Address	Α	Data	Α	Р			
	MSB	LSB	MSB	LSB	Ν	ISB	LSB				

(b) Automatic increment (Select Address increases (+1) according to the number of data.

S	Slave Address	А	Select Address	А	Data1	А	Data2	А		DataN	А	Ρ
	MSB LSB MSB LSB		MS	SB LSB		MSB L	SB	MS	SB LSE	3		
/-												

(Example) ①Data1 shall be set as data of address specified by Select Address.
 ②Data2 shall be set as data of address specified by Select Address +1.

③DataN shall be set as data of address specified by Select Address +N-1.

(c) Configuration unavailable for transmission (In this case, only Select Address1 is set.

S Slav	e Address	Α	Select Add	ress1	Α	Data	Α	Select Ad	dress 2	А	Data	a A	Ρ
MSB	LS	B	MSB	LSB	Μ	SB	SB	MSB	LSB	Μ	ISB	LSB	
	(Note) I	fany	/ data is trans	mitted	as S	Select A	ddres	ss 2 next to a	data, it is	reco	ognize	ed	
		as	data, not as	Select A	ddre	ess 2.							

(4) Slave Address

ſ	MSB							LSB	
	A6	A5	A4	A3	A2	A1	A0	R/W	
	1	0	0	0	0	0	0	0	80H

(5) <u>Select Address & Data</u>

Items	Select Address	MSB			Da	ata			LSB		
nems	(hex)	D7	D6	D5	D4	D3	D2	D1	D0		
Initial setup 1	01	Advanced switch ON/OFF	0	Advanced switch time of Input Gain/Volume Tone/Fader/Loudnes s/Mixing		0	1		switch time ⁄lute		
Initial setup 2	02	LPF Phase	0		er Output lect	0	Su	bwoofer LP	F fc		
Initial setup 3	03	0	0	0	Loudn	less fo	0	0	1		
Input Selector	05	Full-diff Type	0	0	Input selector						
Input gain	06	Mute ON/OFF	0	0			Input Gain				
Volume gain	20			١	/olume Gain	/ Attenuatio	n				
Fader 1ch Front	28				Fader Gain	/ Attenuatior	า				
Fader 2ch Front	29				Fader Gain	/ Attenuatior	า				
Fader 1ch Rear	2A	Fader Gain / Attenuation									
Fader 2ch Rear	2B				Fader Gain	/ Attenuatior	า				
Fader Subwoofer	2C				Fader Gain	/ Attenuatior	า				
Mixing	30				Mixing Gain	/ Attenuation	n				
Bass setup	41	0	0	Bas	s fo	0	0	Bas	ss Q		
Middle setup	44	0	0	Mido	lle fo	0	0	Mide	dle Q		
Treble setup	47	0	0	Treb	le fo	0	0	0	Treble Q		
Bass gain	51	Bass Boost/ Cut	0	0			Bass Gain				
Middle gain	54	Middle Boost/ Cut	0	0	Middle Gain						
Treble gain	57	Treble Boost/ Cut	0	0	Treble Gain						
Loudness Gain	75	0	Loudne	ess Hicut	cut Loudness Gain						
System Reset	FE	1	0	0	0	0	0	0	1		

Advanced switch

Note

- 1. The Advanced Switch works in the latch part while changing from one function to another.
- 2. Upon continuous data transfer, the Select Address rolls over because of the automatic increment function, as shown below.

$$\rightarrow 01 \rightarrow 02 \rightarrow 03 \rightarrow 05 \rightarrow 06 \rightarrow 20 \rightarrow 28 \rightarrow 29 \rightarrow 2A \rightarrow 2B \rightarrow 2C$$

$$\rightarrow 30 \rightarrow 41 \rightarrow 44 \rightarrow 47 \rightarrow 51 \rightarrow 54 \rightarrow 57 \rightarrow 75$$

- 3. Advanced switch is not used for the functions of input selector and subwoofer output select etc. Therefore, please turn on MUTE when changing the settings of this side of a set.
- 4. When using Mute function of this IC at the time of changing input selector, please switch mute ON/OFF for waiting advanced-mute time.

Select address 01 (hex)							
Time	MSB	A	dvanc	ed swi	tch tim	ne of N	lute	LSB
Time	D7	D6	D5	D4	D3	D2	D1	D0
0.6msec	Advanaad		Advanced	switch time			0	0
1.0msec	Advanced Switch	0	of Input ga	ain/Volume	0	1	0	1
1.4msec	ON/OFF	U	Tone/Fade	r/Loudness	0		1	0
3.2msec	UN/OFF		/Miz	xing			1	1

Time	MSB			ed swi /Tone/Fa				LSB
	D7	D6	D5	D4	D3	D2	D1	D0
4.7 msec	A du como o d		0	0				
7.1 msec	Advanced	0	0	1		1	Advanced switch	
11.2 msec	Switch ON/OFF		1	0	0		Time o	of Mute
14.4 msec			1	1				

Mode	MSB		Advar	nced sv	witch C	F	LSB		
Mode	D7	D6	D5	D4	D3	D2	D1	D0	
OFF	0	0	Advanced switch time of Input gain/Volume Tone/Fader/Loudness /Mixing		0	1	Advanced switch		
ON	1	0			0	•	Time o	of Mute	

Select address 02(hex)							
fc	MSB		Sı	lbwoot	fer LPF	LSB		
IC.	D7	D6	D5	D4	D3	D2	D1	D0
OFF						0	0	0
55Hz						0	0	1
85Hz		0	Subwoof	fer Output	0	0	1	0
120Hz	LPF Phase	0 Subwoofel Sele			0	0	1	1
160Hz						1	0	0
Prohibition						Other setting		

Mode	MSB		Subw	oofer C	Dutput	Selec	t	LSB
IVIOUE	D7	D6	D5	D4	D3	D2	D1	D0
LPF			0	0				
Front		0	0	1				- ,
Rear	LPF Phase	0	1	0	0	Su	bwoofer LPF	- IC
Prohibition			1	1				

Phase	MSB				LSB			
Filase	D7	D6	D5	D4	D3	D2	D1	D0
0°	0	0	Subwoof	fer output	0	9	bwoofer LPF	- fo
180°	1	0	se	lect	0	Su		

Select address 03(hex)

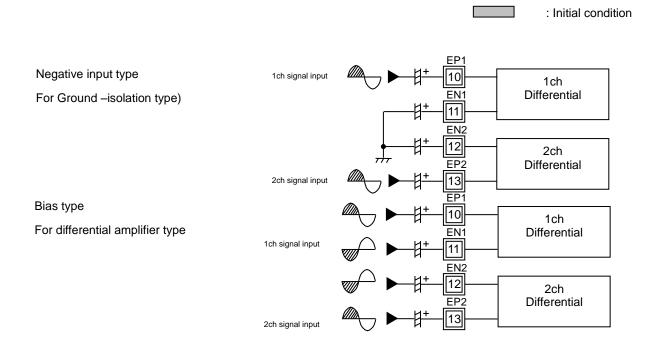
40	MSB			Loud	ness fo			LSB
fO	D7	D6	D5	D4	D3	D2	D1	D0
250Hz				0	0			
400Hz	0	0	0	0	1	0	0	1
800Hz	0			1	0	0		1
Prohibition				1	1			

Select address 05(hex)

Mada		*	MSB		Ir	put S	Select	or		LSB	
Mode	OUTF1	OUTF2	D7	D6	D5	D4	D3	D2	D1	D0	
A	A1	A2			0	0	0	0	0		
В	B1	B2				0	0	0	0	1	
С	C1	C2				0	0	0	1	0	
D single	DP1	DP2				0	0	0	1	1	
E1 single	EP1	EN1	Full-diff bias type 0 select		0	1	0	1	0		
E2 single	EN2	EP2		0	0	1	0	1	1		
A diff	A1	B1		0	0	1	1	1	1		
C diff	B2	C2	Select			1	0	0	0	0	
D diff	DP1	DP2				0	0	1	1	0	
E full diff	EP1	EP2				0	1	0	0	0	
Inp	ut SHORT					0	1	0	0	1	
Prohibition						Other setting					

Input SHORT : The input impedance of each input terminal is lowered from $100k\Omega(Typ)$ to $6 k\Omega(Typ)$. (For quick charge of coupling capacitor)

Mode	MSB		Fu	II-diff Bias	Type Sel	ect		LSB
Nidde	D7	D6	D5	D4	D3	D2	D1	D0
Negative Input	0	0	0	Input Selector				
Bias	1		0	input Selector				



Gain	MSB			Input	Gain			LSE
Gain	D7	D6	D5	D4	D3	D2	D1	D0
0dB				0	0	0	0	0
1dB				0	0	0	0	1
2dB				0	0	0	1	0
3dB				0	0	0	1	1
4dB				0	0	1	0	0
5dB				0	0	1	0	1
6dB				0	0	1	1	0
7dB				0	0	1	1	1
8dB				0	1	0	0	0
9dB				0	1	0	0	1
10dB				0	1	0	1	0
11dB	Mute	0	0	0	1	0	1	1
12dB	ON/OFF	0	0	0	1	1	0	0
13dB				0	1	1	0	1
14dB				0	1	1	1	0
15dB				0	1	1	1	1
16dB				1	0	0	0	0
17dB				1	0	0	0	1
18dB				1	0	0	1	0
19dB				1	0	0	1	1
20dB				1	0	1	0	0
				1	1	0	1	1
Prohibition				:	:	:	:	:
				1	1	1	1	1

Mode	MSB		F	LSE				
Mode	D7	D6	D5	D4	D3	D2	D1	D0
OFF	0	0	0			Input Gain		
ON	1	0	0			Input Gain		

Gain & ATT	MSB		ol, Fad	er Gai	n / Atte	enuatio	on	LSB
Gaill & ATT	D7	D6	D5	D4	D3	D2	D1	D0
	0	0	0	0	0	0	0	0
	0	0	0	0	0	0	0	1
Prohibition	:	:	:	:	:	:	:	:
	0	1	1	1	0	0	0	0
15dB	0	1	1	1	0	0	0	1
14dB	0	1	1	1	0	0	1	0
13dB	0	1	1	1	0	0	1	1
:	:	:	:	:	:	:	:	:
-77dB	1	1	0	0	1	1	0	1
-78dB	1	1	0	0	1	1	1	0
-79dB	1	1	0	0	1	1	1	1
	1	1	0	1	0	0	0	0
Prohibition	:	:	:	:	:	:	:	:
-	1	1	1	1	1	1	1	0
-∞dB	1	1	1	1	1	1	1	1

Select address 20, 28, 29, 2A, 2B, 2C (hex)

Select address 30(hex)

Gain & ATT	MSB		Mixing	Gain	/ Atten	uation	1	LSB
Gaill & ATT	D7	D6	D5	D4	D3	D2	D1	D0
	0	0	0	0	0	0	0	0
	0	0	0	0	0	0	0	1
Prohibition	:	:	:	:	:	:	:	:
	0	1	1	1	1	0	0	0
7dB	0	1	1	1	1	0	0	1
6dB	0	1	1	1	1	0	1	0
5dB	0	1	1	1	1	0	1	1
:	:		:	:	:	:	:	:
-77dB	1	1	0	0	1	1	0	1
-78dB	1	1	0	0	1	1	1	0
-79dB	1	1	0	0	1	1	1	1
	1	1	0	1	0	0	0	0
Prohibition	:	:	:	:	:	:	:	:
	1	1	1	1	1	1	1	0
MIX OFF	1	1	1	1	1	1	1	1

Select address 41(hex)

Q factor	MSB		Ba	ass C	LSB			
	D7	D6	D5	D4	D3	D2	D1	D0
0.5							0	0
1.0	0	0	Bas	o fo	0	0	0	1
1.5	0	0	Das	5 10	0	0	1	0
2.0							1	1

fo	MSB			Bass		LSB		
fo	D7	D6	D5	D4	D3	D2	D1	D0
60Hz			0	0				
80Hz		0	0	1	0	0	Ba	ass actor
100Hz	0	0	1	0	0	0	Q fa	actor
120Hz	7		1	1				

Select address 44(hex)

Q factor	MSB		Mic	Middle		Q factor		LSB
	D7	D6	D5	D4	D3	D2	D1	D0
0.75							0	0
1.0	0	0	Middle	llo fo	0	0	0	1
1.25	0	0	WILCO				1	0
1.5							1	1

fo	MSB			Middle	fo	LSB		
10	D7	D6	D5	D4	D3	D2	D1	D0
500Hz			0	0				
1kHz	0	0	0	1	0	0	Mic	ldle actor
1.5kHz	0	0	1	0	0	0	Q fa	actor
2.5kHz			1	1				

Select address 47 (hex)

Q factor	MSB		Treble (Q factor		LSB	
	D7	D6	D5	D4	D3	D2	D1	D0
0.75	0	0	Treble fo		0	0	0	0
1.25	0	0			0	0	0	1

fo	MSB			Treble	LSB			
fo	D7	D6	D5	D4	D3	D2	D1	D0
7.5kHz	0		0	0			0	
10kHz		0	0	1	0	0		Treble
12.5kHz	U	0	1	0	0	0	0	Q factor
15kHz			1	1				

Cain	MSB	I	Bass/N	/iddle/	Treble	Gain		LS
Gain	D7	D6	D5	D4	D3	D2	D1	Γ
0dB				0	0	0	0	
1dB				0	0	0	0	
2dB				0	0	0	1	
3dB				0	0	0	1	
4dB				0	0	1	0	
5dB				0	0	1	0	
6dB				0	0	1	1	
7dB				0	0	1	1	
8dB				0	1	0	0	
9dB				0	1	0	0	
10dB	Bass/			0	1	0	1	(
11dB	Middle/			0	1	0	1	
12dB	Treble	0	0	0	1	1	0	
13dB	Boost	•		0	1	1	0	
14dB	/cut			0	1	1	1	
15dB				0	1	1	1	
16dB				1	0	0	0	
17dB				1	0	0	0	
18dB				1	0	0	1	
19dB				1	0	0	1	
20dB				1	0	1	0	
				1	0	1	0	
Prohibition				:	:	:	:	
				1	1	1	1	
			-	1	1	1	1	

Mode	MSB	B Bass/Middle/Treble Boost/Cut LS								
Mode	D7	7 D6 D5 D4 D3 D2 D1								
Boost	0	0	0		Base/	Middle/Troble	Cain			
Cut	1	0 0 Bass/Middle/Treble Gain								

Γ

Mada	MSB	B Loudness Hicut LSE								
Mode	D7	D6	D5	D4	D3	D2	D1	D		
Hicut1		0	0		•			•		
Hicut2	0	0	1]		oudness Gai	in			
Hicut3	0	1	0]	L	oudness Ga	In			
Hicut4		1	1							
	MSB			oudne	ss Ga	in		LS		
Gain	D7	D6	D5	D4	D3	D2	D1			
0dB		20	DU	0	0	0	0	0		
1dB				0	0	0	0	1		
2dB				0	0	0	1	0		
3dB				0	0	0	1	1		
4dB				0	0	1	0	0		
5dB				0	0	1	0	1		
6dB				0	0	1	1	0		
7dB				0	0	1	1	1		
8dB				0	1	0	0	0		
9dB				0	1	0	0	1		
10dB				0	1	0	1	0		
11dB				0	1	0	1	1		
12dB	0	Loudne	ss Hicut	0	1	1	0	0		
13dB				0	1	1	0	1		
14dB				0	1	1	1	0		
15dB				0	1	1	1	1		
16dB				1	0	0	0	0		
17dB				1	0	0	0	1		
18dB				1	0	0	1	0		
19dB				1	0	0	1	1		
20dB				1	0	1	0	0		
				1	0	1	0	1		
Prohibition				:	:	:	:	:		
				1	1	1	1	1		

: Initial condition

(6) About Power ON Reset

Built-in IC initialization is made during power ON of the supply voltage. Please send initial data to all addresses at supply voltage on. Also, please turn ON MUTE at the set side until initial data is sent.

Parameter	Symbol		Limit		Unit	Conditions	
Parameter	Symbol	Min	Тур	Max	Unit		
Rise Time of VCC	trise	33	-	-	µsec	V_{CC} rise time from 0V to 5V	
VCC Voltage of Release Power ON Reset	VPOR	-	4.1	-	V		

(7) About External Compulsory Mute Terminal

It is possible to forcibly set Mute from the outside by setting the input voltage at the MUTE terminal.

Mute Voltage Condition	Mode
GND to 1.0V	MUTE ON
2.3V to Vcc	MUTE OFF

Establish the voltage of MUTE in the condition to be defined.

Application Information

1. Function and Specifications

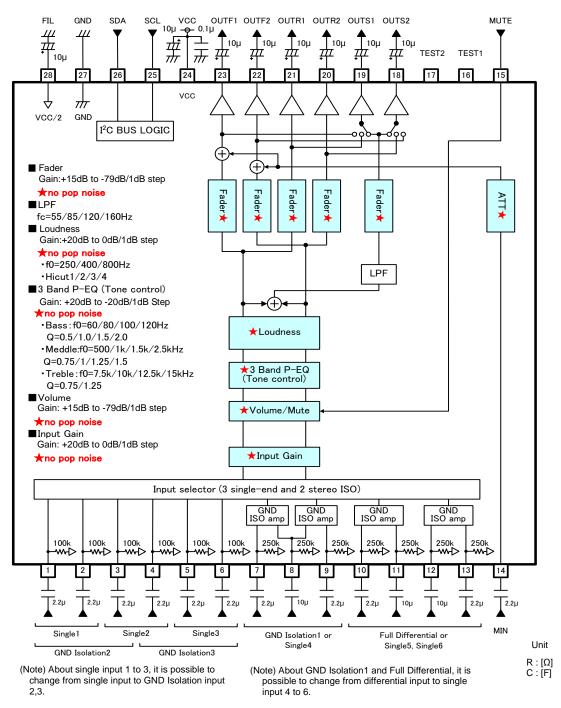
Function	5113		Specifications						
	(Stereo input)								
	· Single-End/Diff/Full-Diff								
	(Possible to set the number of single-end/diff/full-diff as follows)								
Input	Mode 1	Single-End 0	Differential 3	Full-Differential					
selector	Mode 1 Mode 2	1	2	1					
	Mode 3	3	1	1					
	Mode 4	4	0	1					
	Mode 5 Mode 6	5 6	1 0	0					
	Mode 0		ombination of inp	_					
Input	• +20dB to (dB (1dB step)							
gain		· · · ·		evention of switching	noise				
				-					
Mute				evention of switching	noise.				
Volume	• +15dB to -	79dB (1dB ste	ep), -∞dB						
Volumo	 Possible to 	o use "Advanc	ed switch" for pre	evention of switching	noise.				
	・ +20dB to -	20dB (1dB ste	ep)						
	· Q=0.5, 1, 1.5, 2								
Bass	• fo=60, 80, 100, 120Hz								
	Possible to use "Advanced switch" when changing gain								
	 +20dB to -20dB (1dB step) 								
Middle	· Q=0.75, 1, 1.25, 1.5								
inidalo	• fo=500, 1k, 1.5k 2.5kHz								
	Possible to use "Advanced switch" when changing gain								
	• +20dB to ⋅	20dB (1dB ste	ep)						
	· Q=0.75, 1.25								
Treble									
	• fo=7.5k, 10k, 12.5k, 15kHz								
	Possible to use "Advanced switch" when changing gain								
Fader	 +15dB to -79dB(1dB step), -∞dB 								
	Possible to use "Advanced switch" for prevention of switching noise.								
	· 20dB to 0	dB(1dB step)							
Loudness	• fo=250/400/800Hz								
	Possible to use "Advanced switch" for prevention of switching nois								
		20/160Hz, pas	•						
LPF		•	33						
	 Phase shi 	. ,							
	 Monaural 	nput							
Mixing	・+7dB to -7	9dB (1dB step	o), -∞dB						
	 Possible to 	o use "Advanc	ed switch" for pre	evention of switching	noise.				

2. Volume / Fader Volume / Mixing Attenuation of the Details

2. Volume / Fader Volume / Mixing Attenuation of the Details																		
(dB)	[D7	D6	D5	D4	D3	D2	D1	D0	(dB)	D7	D6	D5	D4	D3	D2	D1	D0
+15		0	1	1	1	0	0	0	1	-33	1	0	1	0	0	0	0	1
+14		0	1	1	1	0	0	1	0	-34	1	0	1	0	0	0	1	0
+13		0	1	1	1	0	0	1	1	-35	1	0	1	0	0	0	1	1
+12		0	1	1	1	0	1	0	0	-36	1	0	1	0	0	1	0	0
+11		0	1	1	1	0	1	0	1	-37	1	0	1	0	0	1	0	1
+10		0	1	1	1	0	1	1	0	-38	1	0	1	0	0	1	1	0
+9		0	1	1	1	0	1	1	1	-39	1	0	1	0	0	1	1	1
+8		0	1	1	1	1	0	0	0	-40	1	0	1	0	1	0	0	0
+7		0	1	1	1	1	0	0	1	-41	1	0	1	0	1	0	0	1
+6		0	1	1	1	1	0	1	0	-42	1	0	1	0	1	0	1	0
+5		0	1	1	1	1	0	1	1	-43	1	0	1	0	1	0	1	1
+4		0	1	1	1	1	1	0	0	-44	1	0	1	0	1	1	0	0
+3		0	1	1	1	1	1	0	1	-45	1	0	1	0	1	1	0	1
+2		0	1	1	1	1	1	1	0	-46	1	0	1	0	1	1	1	0
+1		0	1	1	1	1	1	1	1	-47	1	0	1	0	1	1	1	1
0		1	0	0	0	0	0	0	0	-48	1	0	1	1	0	0	0	0
-1		1	0	0	0	0	0	0	1	-49	1	0	1	1	0	0	0	1
-2		1	0	0	0	0	0	1	0	-50	1	0	1	1	0	0	1	0
-3		1	0	0	0	0	0	1	1	-51	1	0	1	1	0	0	1	1
-4		1	0	0	0	0	1	0	0	-52	1	0	1	1	0	1	0	0
-5		1	0	0	0	0	1	0	1	-53	1	0	1	1	0	1	0	1
-6		1	0	0	0	0	1	1	0	-54	1	0	1	1	0	1	1	0
-7		1	0	0	0	0	1	1	1	-55	1	0	1	1	0	1	. 1	1
-8		1	0	0	0	1	0	0	0	-56	1	0	1	1	1	0	0	0
-9		1	0	0	0	1	0	0	1	-57	1	0	1	1	1	0	0	1
-10		1	0	0	0	1	0	1	0	-58	1	0	1	1	1	0	1	0
-11		1	0	0	0	1	0	1	1	-59	1	0	1	1	1	0	1	1
-12		1	0	0	0	1	1	0	0	-60	1	0	1	1	1	1	0	0
-13		1	0	0	0	1	1	0	1	-61	1	0	1	1	1	1	0	1
-14		1	0	0	0	1	1	1	0	-62	1	0	1	1	1	1	1	0
-15		1	0	0	0	1	1	1	1	-63	1	0	1	1	1	1	1	1
-16		1	0	0	1	0	0	0	0	-64	1	1	0	0	0	0	0	0
-17		1	0	0	1	0	0	0	1	-65	1	1	0	0	0	0	0	1
-18		1	0	0	1	0	0	1	0	-66	1	1	0	0	0	0	1	0
-10		1	0	0	1	0	0	1	1	-67	1	1	0	0	0	0	1	1
-20		1	0	0	1	0	1	0	0	-68	1	1	0	0	0	1	0	0
-20		1	0	0	1	0	1	0	1	-69	1	1	0	0	0	1	0	1
-21		1	0	0	1	0	1	1	0	-09 -70	1	1	0	0	0	1	1	0
-22		1	0	0	1	0	1	1	1	-70	1	1	0	0	0	1	1	1
-24			0	0	1	1		0	0	-71	1		0	0	1	0	0	0
-24		1	0	0	1	1	0	0	1	-72	1	1	0	0	1	0	0	1
-25		1	0	0	1	1	0	1	0	-73	1	1	0	0	1	0	1	0
-20		1	0	0	1	1	0	1	1	-74 -75	1	1	0	0	1	0	1	1
-27		1	-	-			-			-75 -76	1		-	-	1	-		
-28		1	0	0	1	1 1	1	0	0	-76 -77	1	1	0	0	1	1	0	0
			-				1	-				1				1	-	
-30 -31		1 1	0	0	1	1	1	1 1	0	-78 -79	1	1	0	0	1	1	1	0
			-							-79 _∞	1					1		
-32		1	0	1	0	0	0	0	0	-00		1	1	1	1	I	1	1

Mixing Adjustable range is +7dB to -∞dB.

3. Application Circuit



Notes on wiring

- ① Please connect the decoupling capacitor of the power supply in the shortest possible distance to GND.
- 2 GND lines should be one-point connected.
- ③ Wiring pattern of Digital shall be away from that of analog unit and crosstalk should not be acceptable.
- ④ If possible, SCL and SDA lines of I²C BUS should not be in parallel. The lines should be shielded, if they are adjacent to each other.
- 5 If possible, analog input lines should not be in parallel. The lines should be shielded, if they are adjacent to each other.
- 6 TEST pins (Pin 16, 17) should be OPEN.

Power Dissipation

About the thermal design of the IC

Characteristics of an IC are greatly affected by the temperature at which it is used exceeding absolute maximum ratings may degrade and destroy the device. Careful consideration must be given to the heat of the IC from the two standpoints of immediate damage and long-term reliability of operation.

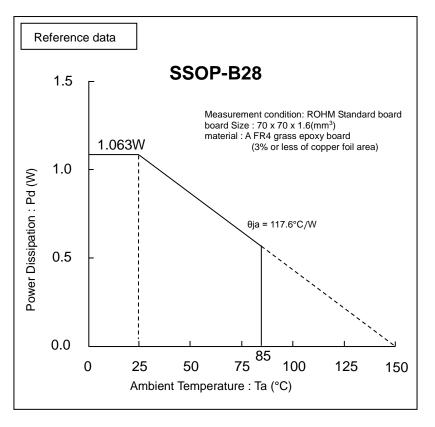


Figure 23. Temperature Derating Curve

(Note) Values are actual measurements and are not guaranteed.

Power dissipation values vary according to the board on which the IC is mounted.

I/O Equivalent Circuits

Terminal No.	Terminal Name	Terminal Voltage	Equivalent Circuit	Terminal Description
1 2 3 4 5 6	A1 A2 B1 B2 C1 C2	4.25	VCC VCC V V V V V V V V V V V V V V V V	A terminal for signal input. The input impedance is 100kΩ (typ).
7 8 9 10 11 12 13	DP1 DN DP2 EP1 EN1 EN2 EP2	4.25		Input terminal available to Single/Differential mode. The input impedance is 250kΩ (typ).
15	MUTE	-	VCC	A terminal for external compulsory mute. If terminal voltage is High level, the mute is off. And if the terminal voltage is Low level, the mute is ON.
18 19 20 21 22 23	OUTS2 OUTS1 OUTR2 OUTR1 OUTF2 OUTF1	4.25	VCC A GND GND	A terminal for Fader and Subwoofer output.

Values in the pin explanation and input/output equivalent circuit are for reference purposes only. It is not a guaranteed value.

I/O Equivalent Circuits - continued

D Equivalen	t Circuits	- continue	d	
Terminal No.	Terminal Name	Terminal	Equivalent Circuit	Terminal Description
24	VCC	Voltage 8.5		Power supply terminal.
25	SCL	-	VCC	A terminal for clock input of I ² C BUS communication.
26	SDA	-	VCC	A terminal for data input of I ² C BUS communication.
27	GND	0		Ground terminal.
28	FIL	4.25		Voltage for reference bias of analog signal system. The simple precharge circuit and simple discharge circuit for an external capacitor are built in.
14	MIN	4.25	VCC VCC VCC VCC VCC VCC VCC VCC VCC VCC	A terminal for signal input The input impedance is 27kΩ (typ).
16 17	TEST	-		TEST terminal

Values in the pin explanation and input/output equivalent circuit are for reference purposes only. It is not a guaranteed value.

Operational Notes

1. Reverse Connection of Power Supply

Connecting the power supply in reverse polarity can damage the IC. Take precautions against reverse polarity when connecting the power supply, such as mounting an external diode between the power supply and the IC's power supply pins.

2. Power Supply Lines

Design the PCB layout pattern to provide low impedance supply lines. Separate the ground and supply lines of the digital and analog blocks to prevent noise in the ground and supply lines of the digital block from affecting the analog block. Furthermore, connect a capacitor to ground at all power supply pins. Consider the effect of temperature and aging on the capacitance value when using electrolytic capacitors.

3. Ground Voltage

Ensure that no pins are at a voltage below that of the ground pin at any time, even during transient condition.

4. Ground Wiring Pattern

When using both small-signal and large-current ground traces, the two ground traces should be routed separately but connected to a single ground at the reference point of the application board to avoid fluctuations in the small-signal ground caused by large currents. Also ensure that the ground traces of external components do not cause variations on the ground voltage. The ground lines must be as short and thick as possible to reduce line impedance.

5. Thermal Consideration

Should by any chance the power dissipation rating be exceeded the rise in temperature of the chip may result in deterioration of the properties of the chip. In case of exceeding this absolute maximum rating, increase the board size and copper area to prevent exceeding the Pd rating.

6. Recommended Operating Conditions

These conditions represent a range within which the expected characteristics of the IC can be approximately obtained. The electrical characteristics are guaranteed under the conditions of each parameter.

7. Inrush Current

When power is first supplied to the IC, it is possible that the internal logic may be unstable and inrush current may flow instantaneously due to the internal powering sequence and delays, especially if the IC has more than one power supply. Therefore, give special consideration to power coupling capacitance, power wiring, width of ground wiring, and routing of connections.

8. Operation Under Strong Electromagnetic Field

Operating the IC in the presence of a strong electromagnetic field may cause the IC to malfunction.

9. Testing on Application Boards

When testing the IC on an application board, connecting a capacitor directly to a low-impedance output pin may subject the IC to stress. Always discharge capacitors completely after each process or step. The IC's power supply should always be turned off completely before connecting or removing it from the test setup during the inspection process. To prevent damage from static discharge, ground the IC during assembly and use similar precautions during transport and storage.

10. Inter-pin Short and Mounting Errors

Ensure that the direction and position are correct when mounting the IC on the PCB. Incorrect mounting may result in damaging the IC. Avoid nearby pins being shorted to each other especially to ground, power supply and output pin. Inter-pin shorts could be due to many reasons such as metal particles, water droplets (in very humid environment) and unintentional solder bridge deposited in between pins during assembly to name a few.

11. Unused Input Pins

Input pins of an IC are often connected to the gate of a MOS transistor. The gate has extremely high impedance and extremely low capacitance. If left unconnected, the electric field from the outside can easily charge it. The small charge acquired in this way is enough to produce a significant effect on the conduction through the transistor and cause unexpected operation of the IC. So unless otherwise specified, unused input pins should be connected to the power supply or ground line.

Operational Notes – continued

12. Regarding the Input Pin of the IC

This monolithic IC contains P+ isolation and P substrate layers between adjacent elements in order to keep them isolated. P-N junctions are formed at the intersection of the P layers with the N layers of other elements, creating a parasitic diode or transistor. For example (refer to figure below):

When GND > Pin A and GND > Pin B, the P-N junction operates as a parasitic diode. When GND > Pin B, the P-N junction operates as a parasitic transistor.

Parasitic diodes inevitably occur in the structure of the IC. The operation of parasitic diodes can result in mutual interference among circuits, operational faults, or physical damage. Therefore, conditions that cause these diodes to operate, such as applying a voltage lower than the GND voltage to an input pin (and thus to the P substrate) should be avoided.

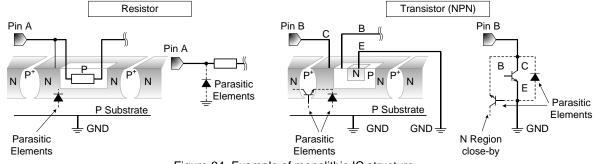
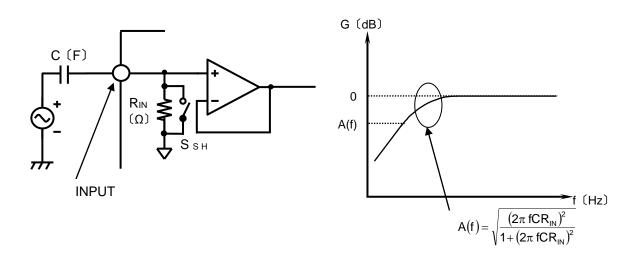


Figure 24. Example of monolithic IC structure

13. About a Signal Input Part

(a) About Input Coupling Capacitor Constant Value

The constant value of input coupling capacitor C(F) is decided with respect to the input impedance $R_{IN}(\Omega)$ at the input signal terminal of the IC that would be sufficient to form an RC characterized HPF.



(b) About the Input Selector SHORT

SHORT mode is the command which makes switch $S_{SH} = ON$ of input selector part so that the input impedance R_{IN} of all terminals becomes small. Switch S_{SH} is OFF when SHORT command is not selected. The constant time brought about by the small resistance inside and the capacitor outside the LSI becomes small when this command is used. The charge time of the capacitor becomes short. Since SHORT mode turns ON the switch of S_{SH} and makes it low impedance, please use it at no signal condition.

14. About Mute Terminal (Pin 15) when Power Supply is OFF

There should be no applied voltage to Mute terminal (Pin 15) when power-supply is OFF. If in case voltage is supplied to MUTE terminal, please insert a series resistor (about $2.2k\Omega$) to Mute terminal. (Please refer to Application Circuit Diagram.)

15. About TEST Pin

TEST Pin should be OPEN. Pin 16,17 are TEST Pins.

Operational Notes – continued

16. About Mixing

(a) <u>About Specification of Fader -∞ at Mixing ON.</u>

Mixed signal is added to the Main signal together with the Fader Gain (+15dB to -79dB) shown in the figure below. When Fader is set up in $-\infty$, the signal after MIX is added with MUTE because the $-\infty$ circuit of Fader is in the step after the addition circuit.

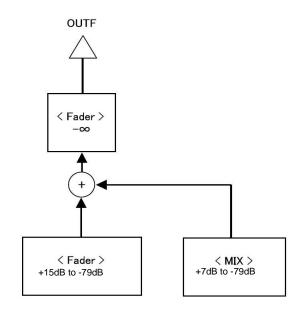
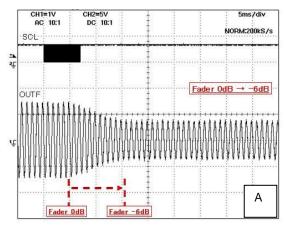


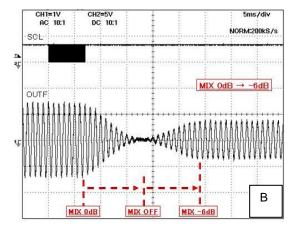
Figure 25. About Front Fader and Mixing

(b) About Advanced switching of Mixing Gain/ATT

When advanced switching of Mixing Gain/ATT works, Mixing becomes a switching movement that it passes through the state of Mixing OFF like what is shown in Figure B (from present setup of Mixing Gain/ATT to Mixing OFF to a target setup of Mixing Gain/ATT).



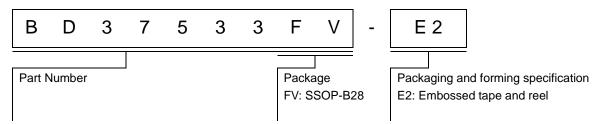
Fader Gain/ATT 0dB to -6dB Advanced Switching



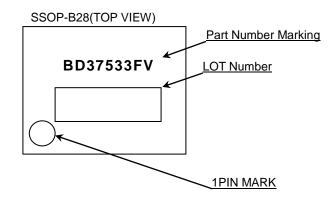
Mixing Gain/ATT 0dB to -6dB Advanced Switching

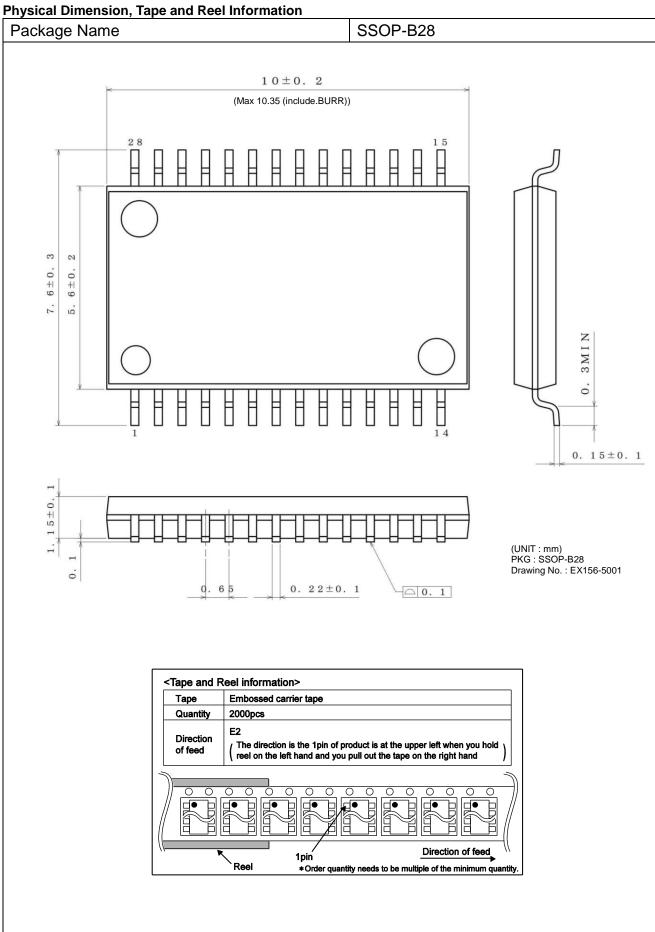
Figure 26. Advanced Switching Movement when Mixing Gain/ATT is changed

Ordering Information



Marking Diagram





Revision History

Date	Revision	Changes
16.Dec.2015	001	New Release

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JAPAN	USA	EU	CHINA
CLASSⅢ	CLASSⅢ	CLASS II b	
CLASSⅣ	CLASSII	CLASSⅢ	CLASSII

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 - [c] the Products are exposed to direct sunshine or condensation
 - [d] the Products are exposed to high Electrostatic
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- 3. Store / transport cartons in the correct direction, which is indicated on a carton with a symbol. Otherwise bent leads may occur due to excessive stress applied when dropping of a carton.
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